

IN THE SPECIFICATION:

Page 17, amend the abstract as follows:

The invention pertains to a A method and a device for thermally connecting the terminal areas (26, 27) of a contact substrate (11) to the terminal areas (28, 29) of a carrier substrate (12), wherein where the substrates (11,12) are, in order to produce the connection, arranged in a connecting position such that the terminal areas (26, 28; 27, 29) are situated opposite one another in the plane of the connection, wherein the contact substrate (11) is heated to the connecting temperature from its rear side that is situated opposite the terminal areas (26, 27) in order to reach the required connecting temperature in the plane of the connection, and wherein where the contact substrate (11) is heated by subjecting the substrate to laser energy.